

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1-22. (Canceled)

23. (Currently amended) An EMI/RFI shielding device comprising:
a shaped polymer substrate comprised of a metallized polymer substrate, wherein
the shaped polymer substrate is substantially conductive; and
a conductive material on at least one surface of the shaped polymer substrate;
wherein the shaped polymer substrate comprises polyvinyl chloride,
polycarbonate, polybutylene terephthalate, or polyethylene terephthalate glycol; and
wherein the shaped polymer substrate is shaped to have an enclosure for enclosing
an electronic component.

24. (Canceled)

25. (Previously presented) The EMI/RFI shielding device of claim 23
wherein the conductive material comprises aluminum.

26. (Previously presented) The EMI/RFI shielding device of claim 23
wherein the conductive material comprises a substantially uniform thickness over at least one
surface of the shaped polymer substrate.

27. (Canceled)

28. (Currently amended) An EMI/RFI shielding device comprising:
a shaped polymer substrate comprised of a metallized polymer substrate, wherein
the shaped polymer substrate is substantially conductive; and

a conductive material on at least one surface of the shaped polymer substrate; wherein the shaped polymer substrate comprises:
a first surface;
a plurality of sidewalls that comprise a first end and a second end, wherein a first end of each of the sidewalls are coupled to the first surface, wherein the sidewalls extend at an angle from the first surface, wherein the first surface and sidewalls define an enclosure portion; and
a peripheral flange coupled to the second end of the sidewalls that extends around the enclosure portion; and
wherein the shaped polymer substrate is shaped to have an enclosure for enclosing an electronic component.

29-31. (Canceled)

32. (Currently amended) An EMI/RFI shield comprising:
a thermoformed thin-walled shape formed of a recycled metallized polymeric material, wherein the thermoformed thin-walled shape comprises an inner surface, an outer surface and edges, and wherein the polymeric material comprises polyvinyl chloride, polycarbonate, polybutylene terephthalate, or polyethylene terephthalate glycol, and wherein the polymeric material is shaped to have an enclosure for enclosing an electronic component; and
a conductive material deposited on at least one of the inner surface and outer surface, wherein the conductive coating comprises a substantially even thickness between 1 micron to 50 microns.

33. (Canceled)

34. (Currently amended) An EMI/RFI shield comprising:
a thermoformed thin-walled shape formed of a recycled metallized polymeric material, wherein the thermoformed thin-walled shape comprises:
an inner surface, an outer surface and edges;
a first surface;
a plurality of sidewalls that comprise a first end and a second end, wherein a first end is coupled to the first surface, wherein the sidewalls extend at an angle from the first surface, wherein the first surface and sidewalls define an enclosure portion;
a peripheral flange coupled to the second end of the sidewalls that extends around the enclosure portion; and
a conductive material deposited on at least one of the inner surface and outer surface, wherein the conductive coating comprises a substantially even thickness between 1 micron to 50 microns; and
wherein the polymeric material is shaped to have an enclosure for enclosing an electronic component.

35-45. (Canceled)

46. (Previously presented) The EMI/RFI shielding device of claim 23 further comprising grinding and re-extruding a metal material along with the polymer substrate.

47-48. (Canceled)

49. (Previously presented) The EMI/RFI shielding device of claim 23 wherein the conductive material comprises copper.

50. (Previously presented) The EMI/RFI shielding device of claim 23 wherein the conductive material comprises nickel.

51-52. (Canceled)